



- Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
- Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
- Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
- Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.
- Z25.1 ■ Cut the thermal pad(Part Number#GPU0US-0.125-AC-0816) for the shape and size of the inner surface of the heatsink(Part Number#MCH054) and paste it on the inner surface of the heatsink;
- Z25.2 ■ Bring the heatsink onto the PCB bottom side (Opposite side of AOP device). Match the teeth in the heatsink with break-away area in the PCB and press the heatsink onto the PCB slightly so as thermal pad is spread all over the area

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.  
ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PROC091	REV: F	SUN REV: Not In VersionControl
M5 Assembly Top	TID #:	N/A	
PLOT NAME = Top Assembly Drawing	GENERATED	: 11-11-2020 20:20:07	TEXAS INSTRUMENTS



PCB VIEWED FROM BOTTOM SIDE	BOARD #: PROC091	REV: F	SUN REV: Not In VersionControl
	TID #: N/A	M6 Assembly Bottom	
PLOT NAME = Bottom Assembly Drawing	GENERATED : 11-11-2020 20:20:07		TEXAS INSTRUMENTS